

- ✓ L9: (12005) 7 same 8
- ✓ L10: (621) 9 and 4
- ✓ L11: (1635273) computer microcomputer micro adj computer cpu
- ✓ L12: (1515518) memory
- ✓ L13: (166) 10 and 11 end 12
- ✓ L14: (2) "02103793"
- ✓ L15: (311715) ((printed adj circuit PC wiring) adj (board card module)) pcb PWB
- ✓ L16: (34880) 15 same 11
- ✓ L17: (427170) 12 same 11
- ✓ L18: (1086) 7 with 12
- ✓ L19: (9885) 11 with 8
- ✓ L20: (17549) 16 and 17
- ✓ L22: (4) 21 and 19
- ✓ L23: (0) 6617694.URPN
- ✓ L24: (0) 6617694.URPN
- ✓ L25: (2) ("8328881" | "8426560")PN
- ✓ L26: (59) 10 and 18
- ✓ L28: (2511) RENESAS.as
- ✓ L27: (3) 10 and 26
- ✓ L28: (260) "thai luen" .xe
- ✓ L29: (2) 28 and 28
- ✓ L30: (0) "thai luen" .pa
- ✓ L31: (37) "thai luen" .xp
- ✓ L32: (4) 28 and 31

Failed

Saved

Aug 2 2004

USPAT-US PCT/EP, EPO, IPO, DIVERVENT, IBM, TDB

Default operator: OR

Plurals Highlight all but terms initially

20 and 18

US	Invator	Document	Issue Date	Title	Current	Current XN	Review	S	C	F	P	Image Date	P
1	<input type="checkbox"/>	Takizawa, M	US 2004015 2004045	Semiconductor integrated circuit device and	257/383			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2004015	
2	<input type="checkbox"/>	Harari, Eliyah	US 2004008 2004042	Universal non-volatile memory card used with	235/441			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2004008	
3	<input type="checkbox"/>	Miwa, Takao	US 2004002 2004042	Semiconductor device	365/199			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2004002	
4	<input type="checkbox"/>	Spartiotis, K	US 2004000 20040402	Radiation imaging system, device and method	250/208			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2004000	
5	<input type="checkbox"/>	Ohnuma, Hide	US 2003023 2003013	Semiconductor device and a method for fabri	438/166-257/E21.70			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2003023	
6	<input type="checkbox"/>	Gann, Keith D	US 2003022 2003012	Method for making stacked integrated circuit	29/840-174/250			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2003022	
7	<input type="checkbox"/>	Takayama, T	US 2003021 2003013	Method of transferring a laminate and method	156/249-156/230			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2003021	
8	<input type="checkbox"/>	Huang, Ying	US 2003014 2003003	Dielectrophoretic separation and immunoass	204/547-204/843			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2003014	
9	<input type="checkbox"/>	Ichijo, Mitsu	US 2003008 2003005	Method of manufacturing a semiconductor d	438/166-257/E21.13			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2003008	
10	<input type="checkbox"/>	Suzuki, Makoto	US 2003007 2003004	Semiconductor device and method of manufa	257/734			<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 2003007	

[] [] [] []

Ready